CENG 4480 L08 Memory 2 Bei Yu

Reference:

- Chapter 11 Memories
- CMOS VLSI Design—A Circuits and Systems Perspective
- by H.E.Weste and D.M.Harris



香港中文大學 The Chinese University of Hong Kong

CENG4480 v.s. CENG3420

• CENG3420:

- architecture perspective
- memory coherent
- data address

• CENG4480: more details on how data is stored

Memory Arrays



Storage based on Feedback

• What if we add feedback to a pair of inverters?



- Usually drawn as a ring of cross-coupled inverters
- Stable way to store one bit of information (w. power)





How to change the value stored?

- Replace inverter with NAND gate
- RS Latch







12T SRAM Cell

- Basic building block: SRAM Cell
 - Holds one bit of information, like a latch
 - Must be read and written
- 12-transistor (12T) SRAM cell
 - Use a simple latch connected to bitline
 - 46 x 75 λ unit cell





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nMOS, pMOS, Inverter

- nMOS:
 - Gate = 1, transistor is ON
 - Then electric current path
- pMOS:
 - Gate = 0, transistor is ON
 - Then electric current path

• Inverter:

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◆ Q = NOT (A)





6T SRAM Cell

- Used in most commercial chips
- A pair of weak cross-coupled inverters
- Data stored in cross-coupled inverters
- Compared with 12T SRAM, 6T SRAM:
 - (+) reduce area

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(-) much more complex control



6T SRAM Read

- Precharge both bitlines high
- Then turn on wordline
- One of the two bitlines will be pulled down by the cell
- Read stability
 - A must not flip
 - N1 >> N2





EX: 6T SRAM Read

• Question 1: A = 0, A_b = 1, discuss the behavior:

Question 2: At least how many bit lines to finish read?



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6T SRAM Write

- Drive one bitline high, the other lowword
- Then turn on wordline
- Bitlines overpower cell with new value
- Writability
 - Must overpower
 - feedback inverter
 - N4 >> P2
 - N2 >> P1 (symmetry)





EX: 6T SRAM Write

• Question 1: A = 0, A_b = 1, discuss the behavior:

• Question 2: At least how many bit lines to finish write?



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6T SRAM Sizing

- High bitlines must not overpower inverters during reads
- But low bitlines must write new value into cell



Memory Arrays



Dynamic RAM (DRAM)

- Basic Principle: Storage of information on capacitors
- Charge & discharge of capacitor to change stored value
- Use of transistor as "switch" to:
 - Store charge
 - Charge or discharge

4T DRAM Cell

Remove the two p-MOS transistors from static RAM cell, to get a four-transistor dynamic RAM cell.



- Data must be refreshed regularly
- Dynamic cells must be designed very carefully
- Data stored as charge on gate capacitors (complementary nodes)

3T DRAM Cell

- No constraints on device ratios
- Reads are non-destructive
- Value stored at node X when writing a "1" = $V_{DD}-V_T$



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3T DRAM Layout





[1970: Intel 1003]

- 576 λ 3T DRAM v.s. 1092 λ 6T SRAM
- Further simplified

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1T DRAM Cell



Need sense amp helping reading

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- Read:
 - Pre-charge large tank to VDD/2
 - If Ts = 0, for large tank : VDD/2 V1
 - If Ts = 1, for large tank: VDD/2 + V1
 - V1 is very insignificant
 - Need sense amp

1T DRAM Cell

- Write: Cs is charged or discharged by asserting WL and BL
- Read: Charge redistribution takes place between bit line and storage capacitance
- Voltage swing is small; typically around 250 mV





Trench-capacitor cell [Mano87]

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EX. 1T DRAM Cell

- Question: VDD=4V, CS=100pF, CBL=1000pF. What's the voltage swing value?
- Note: $\Delta V = \frac{V_{DD}}{2} \cdot \frac{C_S}{C_S + C_{BL}}$

SRAM v.s. DRAM

Static (SRAM)

- Data stored as long as supply is applied
- Large (6 transistors/cell)
- Fast
- Compatible with current CMOS manufacturing

Dynamic (DRAM)

- Periodic refresh required
- Small (1-3 transistors/cell)
- Slower
- Require additional process for trench capacitance

Array Architecture

2ⁿ words of 2^m bits each

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Good regularity – easy to design



SRAM Memory Structure

• Latch based memory



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Array Architecture

- 2ⁿ words of 2^m bits each
- How to design if n >> m?
- Fold by 2k into fewer rows of more columns



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Decoders

- n:2ⁿ decoder consists of 2ⁿ n-input AND gates
 - One needed for each row of memory
 - Build AND with NAND or NOR gates

Static CMOS

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Using NOR gates







А	В	Output
0	0	1
0	1	0
1	0	0
1	1	0

EX. Decoder

Question: AND gates => NAND gate structure



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Large Decoders

- For n > 4, NAND gates become slow
 - Break large gates into multiple smaller gates



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Predecoding

Many of these gates are redundant A2

- Factor out common gates
- => Predecoder
- Saves area
- Same path effort



• Question: How many NANDs can be saved?

Decoder Layout

- Decoders must be pitch-matched to SRAM cell
 - Requires very skinny gates



Column Circuitry

- Some circuitry is required for each column
 - Bitline conditioning
 - Column multiplexing
 - *Sense amplifiers (DRAM)



SRAM from ARM



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Bitline Conditioning

• Precharge bitlines high before reads



 Equalize bitlines to minimize voltage difference when using sense amplifiers



Twisted Bitlines

- Sense amplifiers also amplify noise
 - Coupling noise is severe in modern processes
 - Try to couple equally onto bit and bit_b
 - Done by *twisting* bitlines



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SRAM Column Example





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Column Multiplexing

• Recall that array may be folded for good aspect ratio

- Ex: 2 kword x 16 folded into 256 rows x 128 columns
 - Must select 16 output bits from the 128 columns
 - Requires 16 8:1 column multiplexers

Ex: 2-way Muxed SRAM



Tree Decoder Mux

- Column mux can use pass transistors
 - Use nMOS only, precharge outputs
- One design is to use k series transistors for 2^k:1 mux
 - No external decoder logic needed



*Sense Amplifiers (DRAM)

- Bitlines have many cells attached
 - Ex: 32-kbit SRAM has 256 rows x 128 cols
 - 256 cells on each bitline
- $t_{pd} \propto$ (C/I) ΔV
 - Even with shared diffusion contacts, 64C of diffusion capacitance (big C)
 - Discharged slowly through small transistors (small I)
- Sense amplifiers are triggered on small voltage swing (reduce ΔV)

*Differential Pair Amp

- Differential pair requires no clock
- But always dissipates static power



*Clocked Sense Amp

- Clocked sense amp saves power
- Requires sense_clk after enough bitline swing
- Isolation transistors cut off large bitline capacitance



*Sense Amp Operation for 1T DRAM



- 1T DRAM read is destructive
- Read and refresh for 1T DRAM

Thank You :-)



